

EPEPS 2024

October 6-9, 2024 – Toronto, Canada

**33rd IEEE Conference on
Electrical Performance of
Electronic Packaging and
Systems**



33rd IEEE Conference on Electrical Performance of Electronic Packaging and Systems

www.epeps.org

Dear colleague,

A month is left to submit your work to EPEPS 2024 this October, and apply for student grants! We invite you to:

- [submit a paper](#) and compete for [four conference awards](#)! Deadline: June 14, 2024
- [apply](#) to 15+ **grants for graduate students and young professionals**, sponsored by the EPS and MTT societies. If selected, you'll receive **free registration** and a **travel allowance** to join EPEPS 2024. Deadline: June 14, 2024
- apply to [sponsorship & exhibitor opportunities](#), and promote your company in one of the world's largest tech hubs.

There are many reasons to join EPEPS 2024:

- **top-notch 4-day program**, with 3 keynotes, presentations, posters and demo sessions focused on the latest advancements from academia and industry;
- **four prestigious awards** for the best contributions;
- a full day of **tutorials** on heterogeneous integration, advanced packaging, mm-wave ICs, signal integrity, quantum devices;
- [Toronto](#) is the fastest growing tech hub in North America, home of a talent pool of 400,000+ post-secondary students, and one of the most vibrant and multicultural cities in the world
- visit [Canada](#) in its most spectacular season, with Fall colors in full swing and the Niagara Falls only 1.5 hours away!

Important dates

- **Paper submission:** June 14, 2024 ([see template and instructions here](#))
- **Acceptance:** end of July 2024
- **Sponsor registration:** August 6th, 2024
- **Early bird registration:** September 6th, 2024

Special Issue of IEEE Transactions

Some of the papers that are presented at EPEPS 2024 will have the opportunity to submit a full-length version for a Special Issue of IEEE Transactions on Components, Packaging and Manufacturing Technology.